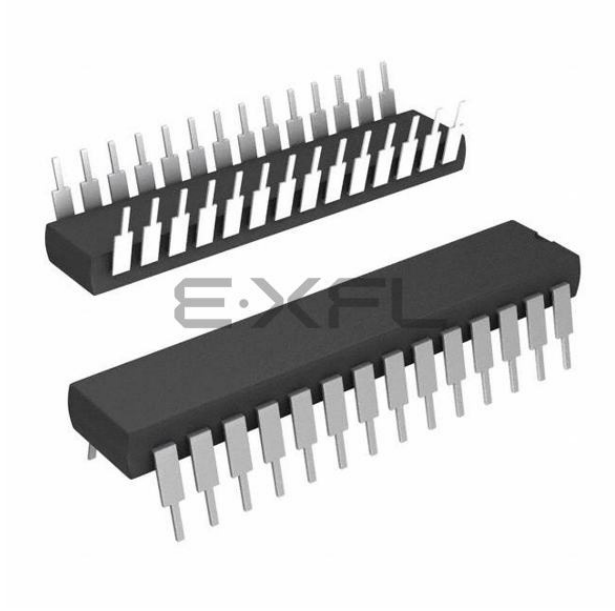

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 19x10b/12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f16km202-e-sp

Device	Pins	Memory			Voltage Range (V)	Peripherals												ICD BRKPT
		Flash Program (bytes)	SRAM (bytes)	EE Data (bytes)		16-Bit Timer	16-Bit MCCP/SCCP	MSSP	UART	12-Bit A/D Channels	8-Bit DAC	Op Amp	Comparators	CTMU	RTCC	CLC	
5V Devices																		
PIC24FV16KM204	44	16K	2K	512	2.0-5.5	1	3/2	2	2	22	2	2	3	Yes	Yes	2	3
PIC24FV16KM202	28	16K	2K	512	2.0-5.5	1	3/2	2	2	19	2	2	3	Yes	Yes	2	3
PIC24FV08KM204	44	8K	2K	512	2.0-5.5	1	3/2	2	2	22	2	2	3	Yes	Yes	2	3
PIC24FV08KM202	28	8K	2K	512	2.0-5.5	1	3/2	2	2	19	2	2	3	Yes	Yes	2	3
PIC24FV16KM104	44	16K	1K	512	2.0-5.5	1	1/1	1	1	22	—	—	1	Yes	—	1	3
PIC24FV16KM102	28	16K	1K	512	2.0-5.5	1	1/1	1	1	19	—	—	1	Yes	—	1	3
PIC24FV08KM102	28	8K	1K	512	2.0-5.5	1	1/1	1	1	19	—	—	1	Yes	—	1	3
PIC24FV08KM101	20	8K	1K	512	2.0-5.5	1	1/1	1	1	16	—	—	1	Yes	—	1	3
3V Devices																		
PIC24F16KM204	44	16K	2K	512	1.8-3.6	1	3/2	2	2	22	2	2	3	Yes	Yes	2	3
PIC24F16KM202	28	16K	2K	512	1.8-3.6	1	3/2	2	2	19	2	2	3	Yes	Yes	2	3
PIC24F08KM204	44	8K	2K	512	1.8-3.6	1	3/2	2	2	22	2	2	3	Yes	Yes	2	3
PIC24F08KM202	28	8K	2K	512	1.8-3.6	1	3/2	2	2	19	2	2	3	Yes	Yes	2	3
PIC24F16KM104	44	16K	1K	512	1.8-3.6	1	1/1	1	1	22	—	—	1	Yes	—	1	3
PIC24F16KM102	28	16K	1K	512	1.8-3.6	1	1/1	1	1	19	—	—	1	Yes	—	1	3
PIC24F08KM102	28	8K	1K	512	1.8-3.6	1	1/1	1	1	19	—	—	1	Yes	—	1	3
PIC24F08KM101	20	8K	1K	512	1.8-3.6	1	1/1	1	1	16	—	—	1	Yes	—	1	3

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4.0 MEMORY ORGANIZATION

As with Harvard architecture devices, the PIC24F microcontrollers feature separate program and data memory space and busing. This architecture also allows the direct access of program memory from the Data Space (DS) during code execution.

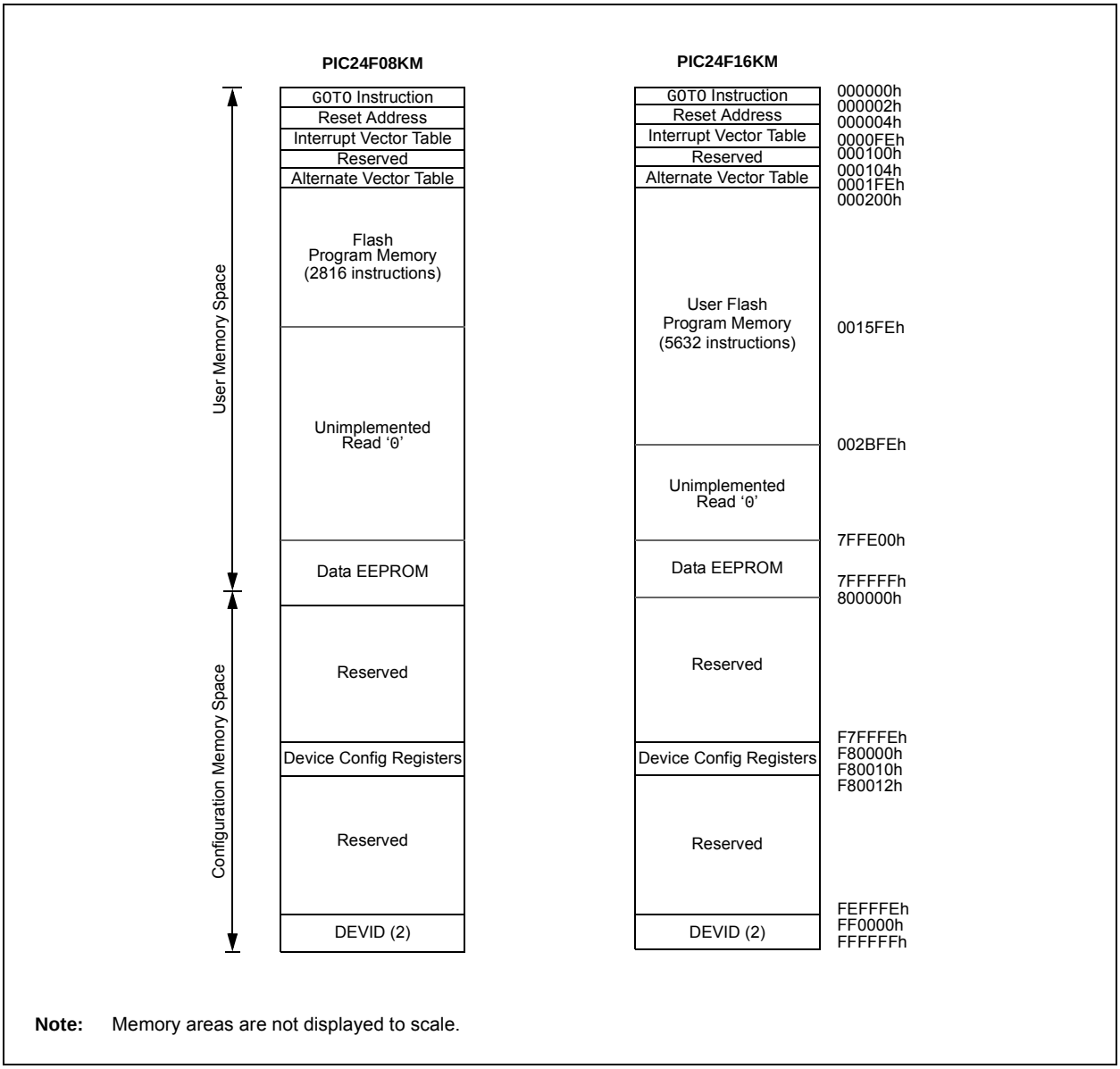
4.1 Program Address Space

The program address memory space of the PIC24F devices is 4M instructions. The space is addressable by a 24-bit value derived from either the 23-bit Program Counter (PC) during program execution, or from a table operation or Data Space remapping, as described in **Section 4.3 "Interfacing Program and Data Memory Spaces"**.

The user access to the program memory space is restricted to the lower half of the address range (000000h to 7FFFFFh). The exception is the use of TBLRD/TBLWT operations, which use TBLPAG<7> to permit access to the Configuration bits and Device ID sections of the configuration memory space.

Memory maps for the PIC24FV16KM204 family of devices are displayed in Figure 4-1.

FIGURE 4-1: PROGRAM SPACE MEMORY MAP FOR PIC24FXXXXX FAMILY DEVICES



Note: Memory areas are not displayed to scale.

TABLE 8-1: TRAP VECTOR DETAILS

Vector Number	IVT Address	AIVT Address	Trap Source
0	000004h	000104h	Reserved
1	000006h	000106h	Oscillator Failure
2	000008h	000108h	Address Error
3	00000Ah	00010Ah	Stack Error
4	00000Ch	00010Ch	Math Error
5	00000Eh	00010Eh	Reserved
6	000010h	000110h	Reserved
7	000012h	000112h	Reserved

TABLE 8-2: IMPLEMENTED INTERRUPT VECTORS

Interrupt Source	Vector Number	IVT Address	AIVT Address	Interrupt Bit Locations		
				Flag	Enable	Priority
ADC1 – ADC1 Convert Done	13	00002Eh	00012Eh	IFS0<13>	IEC0<13>	IPC3<6:4>
CLC1	96	0000D4h	0001D4h	IFS6<0>	IEC6<0>	IPC24<2:0>
CLC2	97	0000D6h	0001D6h	IFS6<1>	IEC6<1>	IPC24<6:4>
Comparator Interrupt	18	000038h	000138h	IFS1<2>	IEC1<2>	IPC4<10:8>
CTMU	77	0000AEh	0001AEh	IFS4<13>	IEC4<13>	IPC19<6:4>
DAC1 – Buffer Update	78	0000B0h	0001B0h	IFS4<14>	IEC4<14>	IPC19<10:8>
DAC2 – Buffer Update	79	0000B2h	0001B2h	IFS4<15>	IEC4<15>	IPC19<14:12>
HLVD – High/Low-Voltage Detect	72	0000A4h	0001A4h	IFS4<8>	IEC4<8>	IPC18<2:0>
ICN – Input Change Notification	19	00003Ah	00013Ah	IFS1<3>	IEC1<3>	IPC4<14:12>
INT0 – External Interrupt 0	0	000014h	000114h	IFS0<0>	IEC0<0>	IPC0<2:0>
INT1 – External Interrupt 1	20	00003Ch	00013Ch	IFS1<4>	IEC1<4>	IPC5<2:0>
INT2 – External Interrupt 2	29	00004Eh	00014Eh	IFS1<13>	IEC1<13>	IPC7<6:4>
MCCP1 – Capture/Compare	1	000016h	000116h	IFS0<1>	IEC0<1>	IPC0<6:4>
MCCP1 – Time Base	7	000022h	000122h	IFS0<7>	IEC0<7>	IPC1<14:12>
MCCP2 – Capture/Compare	2	000018h	000118h	IFS0<2>	IEC0<2>	IPC0<10:8>
MCCP2 – Time Base	8	000024h	000124h	IFS0<8>	IEC0<8>	IPC2<2:0>
MCCP3 – Capture/Compare	5	00001Eh	00011Eh	IFS0<5>	IEC0<5>	IPC1<6:4>
MCCP3 – Time Base	27	00004Ah	00014Ah	IFS1<11>	IEC1<11>	IPC6<14:12>
MSSP1 – Bus Collision Interrupt	17	000036h	000136h	IFS1<1>	IEC1<1>	IPC4<6:4>
MSSP1 – I^2C™/SPI Interrupt	16	000034h	000134h	IFS1<0>	IEC1<0>	IPC4<2:0>
MSSP2 – Bus Collision Interrupt	50	000078h	000178h	IFS3<2>	IEC3<2>	IPC12<10:8>
MSSP2 – I^2C/SPI Interrupt	49	000076h	000176h	IFS3<1>	IEC3<1>	IPC12<6:4>
NVM – NVM Write Complete	15	000032h	000132h	IFS0<15>	IEC0<15>	IPC3<14:12>
RTCC – Real-Time Clock/Calendar	62	000090h	000190h	IFS3<14>	IEC3<14>	IPC15<10:8>
SCCP4 – Capture/Compare	6	000020h	000120h	IFS0<6>	IEC0<6>	IPC1<10:8>
SCCP4 – Time Base	28	00004Ch	00014Ch	IFS1<12>	IEC1<12>	IPC7<2:0>
SCCP5 – Capture/Compare	22	000040h	000140h	IFS1<6>	IEC1<6>	IPC5<10:8>
SCCP5 – Time Base	41	000066h	000166h	IFS2<9>	IEC2<9>	IPC10<6:4>
TMR1 – Timer1	3	00001Ah	00011Ah	IFS0<3>	IEC0<3>	IPC0<14:12>
UART1 Error	65	000096h	000196h	IFS4<1>	IEC4<1>	IPC16<6:4>
UART2 Error	66	000098h	000198h	IFS4<2>	IEC4<2>	IPC16<10:8>
UART1RX – UART1 Receiver	11	00002Ah	00012Ah	IFS0<11>	IEC0<11>	IPC2<14:12>
UART1TX – UART1 Transmitter	12	00002Ch	00012Ch	IFS0<12>	IEC0<12>	IPC3<2:0>
UART2RX – UART2 Receiver	30	000050h	000150h	IFS1<14>	IEC1<14>	IPC7<10:8>
UART2TX – UART2 Transmitter	31	000052h	000152h	IFS1<15>	IEC1<15>	IPC7<14:12>
ULPWU – Ultra Low-Power Wake-up	80	0000B4h	0001B4h	IFS5<0>	IEC5<0>	IPC20<2:0>

REGISTER 8-26: IPC7: INTERRUPT PRIORITY CONTROL REGISTER 7

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	U2TXIP2	U2TXIP1	U2TXIP0	—	U2RXIP2	U2RXIP1	U2RXIP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	INT2IP2	INT2IP1	INT2IP0	—	CCT4IP2	CCT4IP1	CCT4IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **U2TXIP<2:0>:** UART2 Transmitter Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **U2RXIP<2:0>:** UART2 Receiver Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **INT2IP<2:0>:** External Interrupt 2 Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **CCT4IP<2:0>:** Capture/Compare 4 Timer Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

9.4 Clock Switching Operation

With few limitations, applications are free to switch between any of the four clock sources (POSC, SOSC, FRC and LPRC) under software control and at any time. To limit the possible side effects that could result from this flexibility, PIC24F devices have a safeguard lock built into the switching process.

Note:	The Primary Oscillator mode has three different submodes (XT, HS and EC), which are determined by the POSCMDx Configuration bits. While an application can switch to and from Primary Oscillator mode in software, it cannot switch between the different primary submodes without reprogramming the device.

9.4.1 ENABLING CLOCK SWITCHING

To enable clock switching, the FCKSM1 Configuration bit in the FOSC Configuration register must be programmed to '0'. (Refer to **Section 25.0 "Special Features"** for further details.) If the FCKSM1 Configuration bit is unprogrammed ('1'), the clock switching function and FSCM function are disabled; this is the default setting.

The NOSCx control bits (OSCCON<10:8>) do not control the clock selection when clock switching is disabled. However, the COSCx bits (OSCCON<14:12>) will reflect the clock source selected by the FNOSCx Configuration bits.

The OSWEN control bit (OSCCON<0>) has no effect when clock switching is disabled; it is held at '0' at all times.

9.4.2 OSCILLATOR SWITCHING SEQUENCE

At a minimum, performing a clock switch requires this basic sequence:

1. If desired, read the COSCx bits (OSCCON<14:12>) to determine the current oscillator source.
2. Perform the unlock sequence to allow a write to the OSCCON register high byte.
3. Write the appropriate value to the NOSCx bits (OSCCON<10:8>) for the new oscillator source.
4. Perform the unlock sequence to allow a write to the OSCCON register low byte.
5. Set the OSWEN bit to initiate the oscillator switch.

Once the basic sequence is completed, the system clock hardware responds automatically, as follows:

1. The clock switching hardware compares the COSCx bits with the new value of the NOSCx bits. If they are the same, then the clock switch is a redundant operation. In this case, the OSWEN bit is cleared automatically and the clock switch is aborted.
2. If a valid clock switch has been initiated, the LOCK (OSCCON<5>) and CF (OSCCON<3>) bits are cleared.
3. The new oscillator is turned on by the hardware if it is not currently running. If a crystal oscillator must be turned on, the hardware will wait until the OST expires. If the new source is using the PLL, then the hardware waits until a PLL lock is detected (LOCK = 1).
4. The hardware waits for 10 clock cycles from the new clock source and then performs the clock switch.
5. The hardware clears the OSWEN bit to indicate a successful clock transition. In addition, the NOSCx bits value is transferred to the COSCx bits.
6. The old clock source is turned off at this time, with the exception of LPRC (if WDT, FSCM or RTCC with LPRC as a clock source is enabled) or SOSC (if SOSCEN remains enabled).

Note 1:	The processor will continue to execute code throughout the clock switching sequence. Timing-sensitive code should not be executed during this time.
2:	Direct clock switches between any Primary Oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transitional clock source between the two PLL modes.

10.4 Voltage Regulator-Based Power-Saving Features

The PIC24FV16KM204 family series devices have a voltage regulator that has the ability to alter functionality to provide power savings. The on-chip regulator is made up of two basic modules: the Voltage Regulator (VREG) and the Retention Regulator (RETREG). With the combination of VREG and RETREG, the following power modes are available:

10.4.1 RUN MODE

In Run mode, the main VREG is providing a regulated voltage with enough current to supply a device running at full speed and the device is not in Sleep mode. The RETREG may or may not be running, but is unused.

10.4.2 SLEEP MODE

In Sleep mode, the device is in Sleep and the main VREG is providing a regulated voltage to the core. By default, in Sleep mode, the regulator enters a low-power standby state which consumes reduced quiescent current. The PMSLP bit (RCON<8>) controls the regulator state in Sleep mode. If the PMSLP bit is set, the program Flash memory will stay powered on during Sleep mode and the regulator will stay in its full-power mode.

10.4.3 RETENTION REGULATOR

The Retention Regulator, sometimes referred to as the low-voltage regulator, is designed to provide power to the core at a lower voltage than the standard voltage regulator, while consuming significantly lower quiescent current. Refer to **Section 27.0 "Electrical Characteristics"** for the voltage output range of the RETREG. This regulator is only used in Sleep mode, and has limited output current to maintain the RAM and provide power for limited peripherals, such as the WDT, while the device is in Sleep. It is controlled by the RETCFG Configuration bit (FPOR<2>) and in firmware by the RETEN bit (RCON<12>). RETCFG must be programmed (= 0) and the RETEN bit must be set (= 1) for the Retention Regulator to be enabled.

10.4.4 RETENTION SLEEP MODE

In Retention Sleep mode, the device is in Sleep and all regulated voltage is provided solely by the RETREG, while the main VREG is disabled. Consequently, this mode provides the lowest Sleep power consumption, but has a trade-off of a longer wake-up time. The low-voltage Sleep wake-up time is longer than Sleep mode due to the extra time required to re-enable the VREG and raise the V_{DDCORE} supply rail back to normal regulated levels.

Note:	The PIC24F16KM204 family devices do not have any internal voltage regulation, and therefore, do not support Retention Sleep mode.

TABLE 10-1: VOLTAGE REGULATION CONFIGURATION SETTINGS FOR PIC24FXXXXX FAMILY DEVICES

RETCFG Bit (FPOR<2>)	RETEN Bit (RCON<12>	PMSLP Bit (RCON<8>)	Power Mode During Sleep	Description
0	0	1	Sleep	VREG mode (normal) is unchanged during Sleep. RETREG is unused.
0	0	0	Sleep (Standby)	VREG goes to Low-Power Standby mode during Sleep. RETREG is unused.
0	1	0	Retention Sleep	VREG is off during Sleep. RETREG is enabled and provides Sleep voltage regulation.
1	x	1	Sleep	VREG mode (normal) is unchanged during Sleep. RETREG is disabled at all times.
1	x	0	Sleep (Standby)	VREG goes to Low-Power Standby mode during Sleep. RETREG is disabled at all times.

10.5 Doze Mode

Generally, changing clock speed and invoking one of the power-saving modes are the preferred strategies for reducing power consumption. There may be circumstances, however, where this is not practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed may introduce communication errors, while using a power-saving mode may stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default.

It is also possible to use Doze mode to selectively reduce power consumption in event driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption. Meanwhile, the CPU Idles, waiting for something to invoke an interrupt routine. Enabling the automatic return to full-speed CPU operation on interrupts is enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

10.6 Selective Peripheral Module Control

Idle and Doze modes allow users to substantially reduce power consumption by slowing or stopping the CPU clock. Even so, peripheral modules still remain clocked, and thus, consume power. There may be cases where the application needs what these modes do not provide: the allocation of power resources to CPU processing with minimal power consumption from the peripherals.

PIC24F devices address this requirement by allowing peripheral modules to be selectively disabled, reducing or eliminating their power consumption. This can be done with two control bits:

- The Peripheral Enable bit, generically named, “XXXEN”, located in the module’s main control SFR.
- The Peripheral Module Disable (PMD) bit, generically named, “XXXMD”, located in one of the PMDx Control registers.

Both bits have similar functions in enabling or disabling its associated module. Setting the PMDx bits for a module, disables all clock sources to that module, reducing its power consumption to an absolute minimum. In this state, the control and status registers associated with the peripheral will also be disabled, so writes to those registers will have no effect, and read values will be invalid. Many peripheral modules have a corresponding PMDx bit.

In contrast, disabling a module by clearing its XXXEN bit, disables its functionality, but leaves its registers available to be read and written to. Power consumption is reduced, but not by as much as when the PMDx bits are used. Most peripheral modules have an enable bit; exceptions include capture, compare and RTCC.

To achieve more selective power savings, peripheral modules can also be selectively disabled when the device enters Idle mode. This is done through the control bit of the generic name format, “XXXIDL”. By default, all modules that can operate during Idle mode will do so. Using the disable on Idle feature disables the module while in Idle mode, allowing further reduction of power consumption during Idle mode, enhancing power savings for extremely critical power applications.

REGISTER 13-1: CCPxCON1L: CCPx CONTROL 1 LOW REGISTERS (CONTINUED)

bit 3-0 **MOD<3:0>:** CCPx Mode Select bits

For CCSEL = 1 (Input Capture modes):
1xxx = Reserved
011x = Reserved
0101 = Capture every 16th rising edge
0100 = Capture every 4th rising edge
0011 = Capture every rising and falling edge
0010 = Capture every falling edge
0001 = Capture every rising edge
0000 = Capture every rising and falling edge (Edge Detect mode)

For CCSEL = 0 (Output Compare/Timer modes):
1111 = External Input mode: Pulse generator is disabled, source is selected by ICS<2:0>
1110 = Reserved
110x = Reserved
10xx = Reserved
0111 = Variable Frequency Pulse mode
0110 = Center-Aligned Pulse Compare mode, buffered
0101 = Dual Edge Compare mode, buffered
0100 = Dual Edge Compare mode
0011 = 16-Bit/32-Bit Single Edge mode, toggle output on compare match
0010 = 16-Bit/32-Bit Single Edge mode, drive output low on compare match
0001 = 16-Bit/32-Bit Single Edge mode, drive output high on compare match
0000 = 16-Bit/32-Bit Timer mode, output functions are disabled

Note 1: Clock options are limited in some operating modes. See Table 13-1 for restrictions.

19.0 12-BIT A/D CONVERTER WITH THRESHOLD DETECT

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the 12-Bit A/D Converter with Threshold Detect, refer to the *"PIC24F Family Reference Manual"*, **"12-Bit A/D Converter with Threshold Detect"** (DS39739).

The PIC24F 12-bit A/D Converter has the following key features:

- Successive Approximation Register (SAR) Conversion
- Conversion Speeds of up to 100 ksps
- Up to 32 Analog Input Channels (internal and external)
- Multiple Internal Reference Input Channels
- External Voltage Reference Input Pins
- Unipolar Differential Sample-and-Hold (S/H) Amplifier
- Automated Threshold Scan and Compare Operation to Pre-Evaluate Conversion Results
- Selectable Conversion Trigger Source
- Fixed-Length (one word per channel), Configurable Conversion Result Buffer
- Four Options for Results Alignment
- Configurable Interrupt Generation
- Operation During CPU Sleep and Idle modes

The 12-bit A/D Converter module is an enhanced version of the 10-bit module offered in some PIC24 devices. Both modules are Successive Approximation Register (SAR) converters at their cores, surrounded by a range of hardware features for flexible configuration. This version of the module extends functionality by providing 12-bit resolution, a wider range of automatic sampling options and tighter integration with other analog modules, such as the CTMU, and a configurable results buffer. There is a legacy 10-bit mode on this A/D to allow the option to run with lower resolution in order to obtain higher throughput. This module also includes a unique Threshold Detect feature that allows the module itself to make simple decisions based on the conversion results.

A simplified block diagram for the module is illustrated in Figure 19-1.

REGISTER 19-1: AD1CON1: A/DA/D CONTROL REGISTER 1

R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
ADON	—	ADSIDL	—	—	MODE12	FORM1	FORM0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0, HSC	R/C-0, HSC
SSRC3	SSRC2	SSRC1	SSRC0	—	ASAM	SAMP	DONE
bit 7							bit 0

Legend:	C = Clearable bit	U = Unimplemented bit, read as '0'	
R = Readable bit	W = Writable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADON:** A/D Operating Mode bit
1 = A/D Converter is operating
0 = A/D Converter is off

bit 14 **Unimplemented:** Read as '0'

bit 13 **ADSIDL:** A/D Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-11 **Unimplemented:** Read as '0'

bit 10 **MODE12:** 12-Bit A/D Operation Mode bit
1 = 12-bit A/D operation
0 = 10-bit A/D operation

bit 9-8 **FORM<1:0>:** Data Output Format bits (see the following formats)
11 = Fractional result, signed, left justified
10 = Absolute fractional result, unsigned, left justified
01 = Decimal result, signed, right justified
00 = Absolute decimal result, unsigned, right justified

bit 7-4 **SSRC<3:0>:** Sample Clock Source Select bits
1111 = Reserved
•
•
•
1101 = Reserved
1100 = CLC2 event ends sampling and starts conversion
1011 = SCCP4 Compare Event (CCP4IF) ends sampling and starts conversion
1010 = MCCP3 Compare Event (CCP3IF) ends sampling and starts conversion
1001 = MCCP2 Compare Event (CCP2IF) ends sampling and starts conversion
1000 = CLC1 event ends sampling and starts conversion
0111 = Internal counter ends sampling and starts conversion (auto-convert)
0110 = TMR1 Sleep mode Trigger event ends sampling and starts conversion(1)
0101 = TMR1 event ends sampling and starts conversion
0100 = CTMU event ends sampling and starts conversion
0011 = SCCP5 Compare Event (CCP5IF) ends sampling and starts conversion
0010 = MCCP1 Compare Event (CCP1IF) ends sampling and starts conversion
0001 = INT0 event ends sampling and starts conversion
0000 = Clearing the Sample bit ends sampling and starts conversion

Note 1: This version of the TMR1 Trigger allows A/D conversions to be triggered from TMR1 while the device is operating in Sleep mode. The SSRC<3:0> = 0101 option allows conversions to be triggered in Run or Idle modes only.

23.0 COMPARATOR VOLTAGE REFERENCE

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Comparator Voltage Reference, refer to the *"PIC24F Family Reference Manual"*, **"Comparator Voltage Reference Module"** (DS39709).

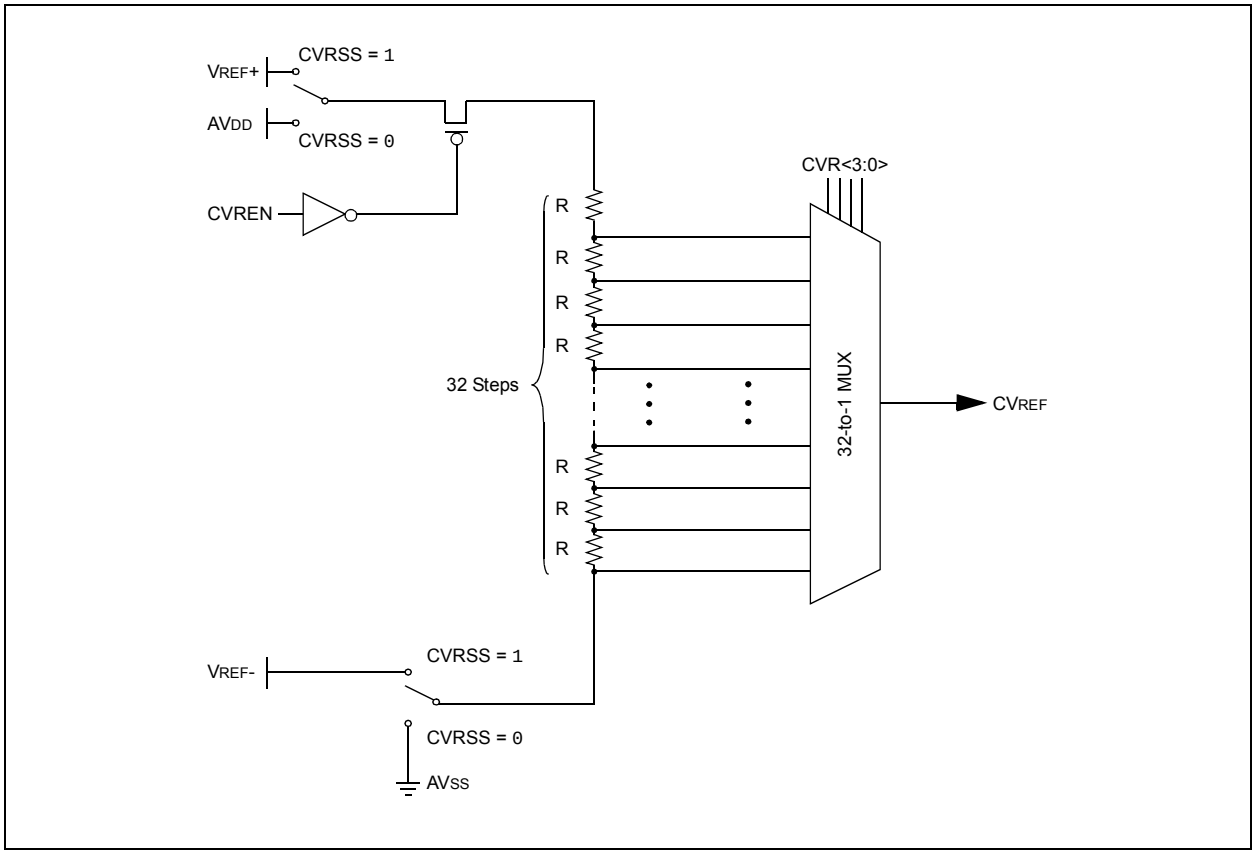
23.1 Configuring the Comparator Voltage Reference

The comparator voltage reference module is controlled through the CVRCON register (Register 23-1). The comparator voltage reference provides a range of output voltages with 32 distinct levels.

The comparator voltage reference supply voltage can come from either VDD and VSS, or the external VREF+ and VREF-. The voltage source is selected by the CVRSS bit (CVRCON<5>).

The settling time of the comparator voltage reference must be considered when changing the CVREF output.

FIGURE 23-1: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



25.2 On-Chip Voltage Regulator

All of the PIC24FXXXXX family devices power their core digital logic at a nominal 3.0V. This may create an issue for designs that are required to operate at a higher typical voltage, as high as 5.0V. To simplify system design, all devices in the "FV" family incorporate an on-chip regulator that allows the device core to run at 3.0V, while the I/O is powered by VDD at a higher voltage.

The regulator is always enabled and provides power to the core from the other VDD pins. A low-ESR capacitor (such as ceramic) must be connected to the VCAP pin (Figure 25-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in **Section 27.1 "DC Characteristics"** and discussed in detail in **Section 2.0 "Guidelines for Getting Started with 16-Bit Microcontrollers"**.

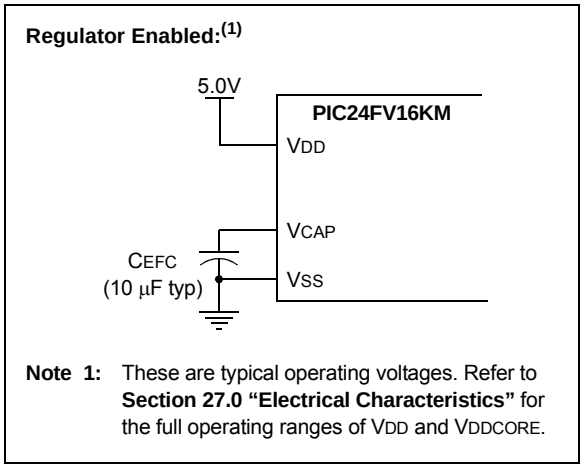
In all of the "F" family of devices, the regulator is disabled. Instead, the core logic is directly powered from VDD. "F" devices operate at a lower range of VDD voltage, from 1.8V-3.6V.

25.2.1 VOLTAGE REGULATOR TRACKING MODE AND LOW-VOLTAGE DETECTION

For all PIC24FXXXXX devices, the on-chip regulator provides a constant voltage of 3.0V nominal to the digital core logic. The regulator can provide this level from a VDD of about 3.2V, all the way up to the device's VDDMAX. It does not have the capability to boost VDD levels below 3.2V. In order to prevent "brown out" conditions when the voltage drops too low for the regulator, the regulator enters Tracking mode. In Tracking mode, the regulator output follows VDD with a typical voltage drop of 150 mV.

When the device enters Tracking mode, it is no longer possible to operate at full speed. To provide information about when the device enters Tracking mode, the on-chip High/Low-Voltage Detect (HLVD) module can be used. The HLVD trip point should be configured so that if VDD drops close to the minimum voltage for the operating frequency of the device, the HLVD Interrupt Flag, HLVDIF (IFS4<8>), will occur. This can be used to generate an interrupt and put the application into a low-power operational mode or trigger an orderly shutdown. Refer to **Section 27.1 "DC Characteristics"** for the specifications detailing the maximum operating speed based on the applied VDD voltage.

FIGURE 25-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR



Note 1: These are typical operating voltages. Refer to **Section 27.0 "Electrical Characteristics"** for the full operating ranges of VDD and VDDCORE.

25.2.2 VOLTAGE REGULATOR START-UP TIME

For PIC24FXXXXX family devices, it takes a short time, designated as TPM, for the regulator to generate a stable output. During this time, code execution is disabled. TPM is applied every time the device resumes operation after any power-down, including Sleep mode. TPM is specified in **Section 27.2 "AC Characteristics and Timing Parameters"**.

25.3 Watchdog Timer (WDT)

For the PIC24FXXXXX family of devices, the WDT is driven by the LPRC Oscillator. When the WDT is enabled, the clock source is also enabled.

The nominal WDT clock source from LPRC is 31 kHz. This feeds a prescaler that can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the FWPSA Configuration bit. With a 31 kHz input, the prescaler yields a nominal WDT Time-out period (TWDT) of 1 ms in 5-bit mode or 4 ms in 7-bit mode.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the Configuration bits, WDTPS<3:0> (FWDT<3:0>), which allow the selection of a total of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler time-out periods, ranges from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSCx bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

If the WDT is enabled in hardware (FWDTEN<1:0> = 11), it will continue to run during Sleep or Idle modes. When the WDT time-out occurs, the device will wake and code execution will continue from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bit (RCON<3:2>) will need to be cleared in software after the device wakes up.

The WDT Flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

Note:	The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

25.3.1 WINDOWED OPERATION

The Watchdog Timer has an optional Fixed Window mode of operation. In this Windowed mode, CLRWDT instructions can only reset the WDT during the last 1/4 of the programmed WDT period. A CLRWDT instruction executed before that window causes a WDT Reset, similar to a WDT time-out.

Windowed WDT mode is enabled by programming the Configuration bit, WINDIS (FWDT<6>), to '0'.

25.3.2 CONTROL REGISTER

The WDT is enabled or disabled by the FWDTEN<1:0> Configuration bits. When both of the FWDTEN<1:0> Configuration bits are set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN<1:0> Configuration bits have been programmed to '10'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user to enable the WDT for critical code segments, and disable the WDT during non-critical segments, for maximum power savings. When the FWDTEN<1:0> bits are set to '01', the WDT is only enabled in Run and Idle modes, and is disabled in Sleep. Software control of the SWDTEN bit (RCON<5>) is disabled with this setting.

FIGURE 25-2: WDT BLOCK DIAGRAM

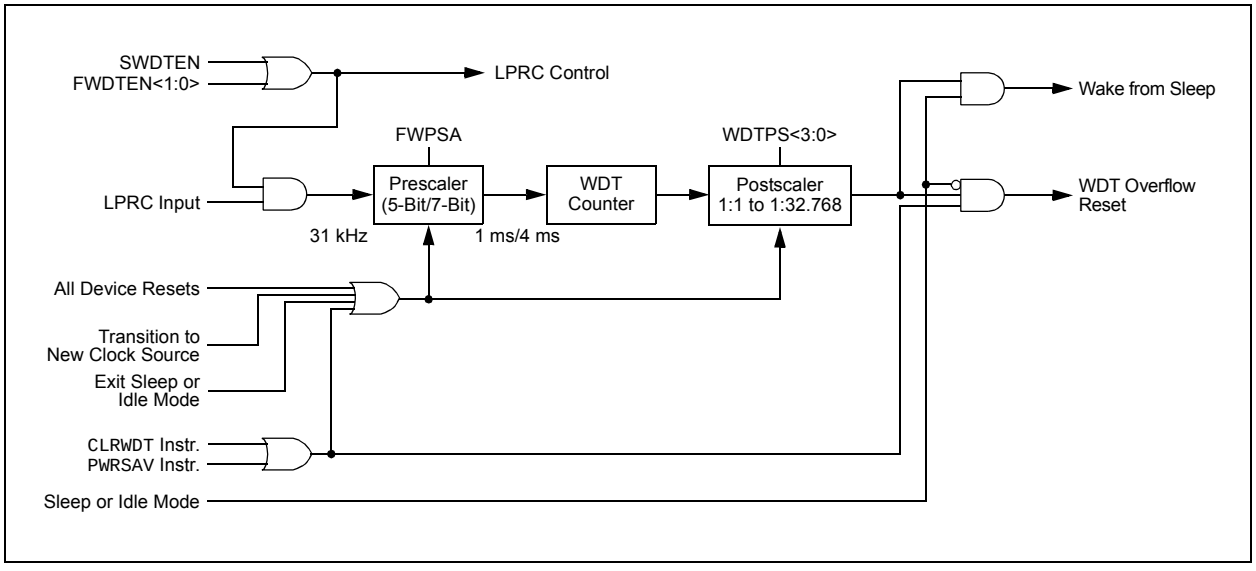


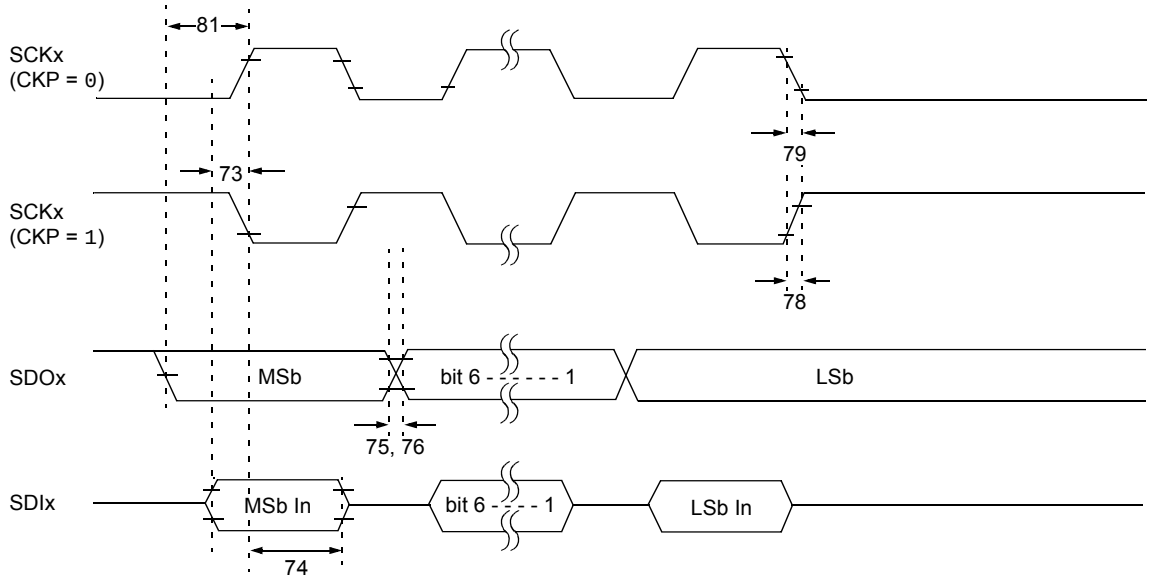
TABLE 27-6: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS		Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KMXXX) 2.0V to 5.5V (PIC24FV16KMXXX) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Device**	**Typical**	**Max**	**Units**	**Conditions**	
IDD Current						
D20	PIC24FV16KMXXX	269	450	µA	2.0V	0.5 MIPS, FOSC = 1 MHz(1)
		465	830	µA	5.0V	
	PIC24F16KMXXX	200	330	µA	1.8V	
		410	750	µA	3.3V	
DC22	PIC24FV16KMXXX	490	—	µA	2.0V	1 MIPS, FOSC = 2 MHz(1)
		880	—	µA	5.0V	
	PIC24F16KMXXX	407	—	µA	1.8V	
		800	—	µA	3.3V	
DC24	PIC24FV16KMXXX	13.0	15.0	mA	5.0V	16 MIPS, FOSC = 32 MHz(1)
	PIC24F16KMXXX	12.0	13.0	mA	3.3V	
DC26	PIC24FV16KMXXX	2.0	—	mA	2.0V	FRC (4 MIPS), FOSC = 8 MHz
		3.5	—	mA	5.0V	
	PIC24F16KMXXX	1.80	—	mA	1.8V	
		3.40	—	mA	3.3V	
DC30	PIC24FV16KMXXX	48.0	250	µA	2.0V	LPRC (15.5 KIPS), FOSC = 31 kHz
		75.0	275	µA	5.0V	
	PIC24F16KMXXX	8.1	28.0	µA	1.8V	
		13.50	55.00	µA	3.3V	

Legend: Unshaded rows represent PIC24F16KMXXX devices and shaded rows represent PIC24FV16KMXXX devices.

Note 1: The oscillator is in External Clock mode (FOSCSEL<2:0> = 010, FOSC<1:0> = 00).

FIGURE 27-12: EXAMPLE SPI MASTER MODE TIMING (CKE = 1)

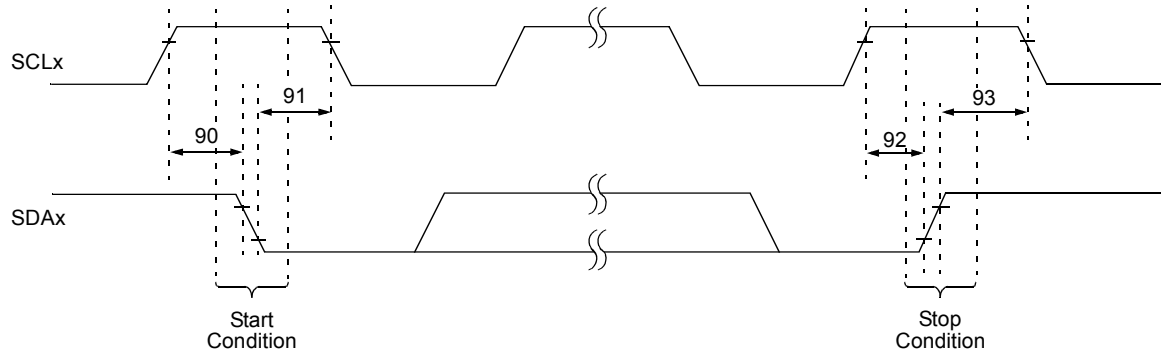


Note: Refer to Figure 27-5 for load conditions.

TABLE 27-30: EXAMPLE SPI MODE REQUIREMENTS (MASTER MODE, CKE = 1)

Param. No.	Symbol	Characteristic	Min	Max	Units	Conditions
73	TDIV2SCH, TDIV2SCL	Setup Time of SDIx Data Input to SCKx Edge	35	—	ns	
74	TSCH2DIL, TSCL2DIL	Hold Time of SDIx Data Input to SCKx Edge	40	—	ns	
75	TDOR	SDOx Data Output Rise Time	—	25	ns	
76	TDOF	SDOx Data Output Fall Time	—	25	ns	
78	TSCR	SCKx Output Rise Time (Master mode)	—	25	ns	
79	TSCF	SCKx Output Fall Time (Master mode)	—	25	ns	
81	TDOV2SCH, TDOV2SCL	SDOx Data Output Setup to SCKx Edge	TCY	—	ns	
	FSCK	SCKx Frequency	—	10	MHz	

FIGURE 27-15: I²C™ BUS START/STOP BITS TIMING

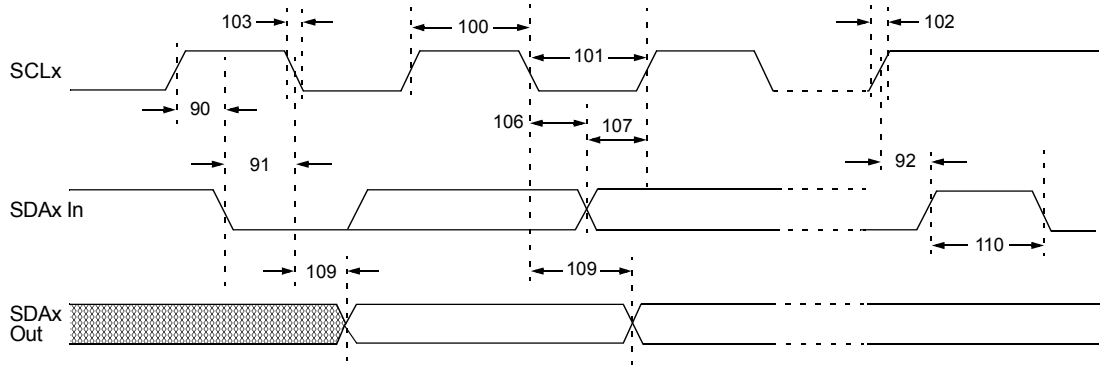


Note: Refer to Figure 27-5 for load conditions.

TABLE 27-33: I²C™ BUS START/STOP BITS REQUIREMENTS (SLAVE MODE)

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
90	TSU:STA	Start Condition Setup Time	100 kHz mode	4700	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—		
91	THD:STA	Start Condition Hold Time	100 kHz mode	4000	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—		
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	4700	—	ns	
			400 kHz mode	600	—		
93	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	
			400 kHz mode	600	—		

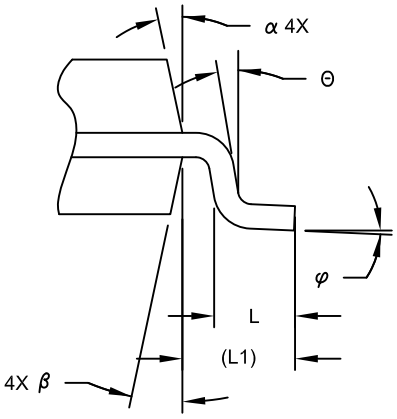
FIGURE 27-16: I²C™ BUS DATA TIMING



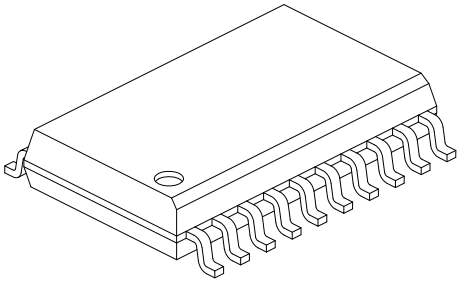
Note: Refer to Figure 27-5 for load conditions.

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		12.80 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

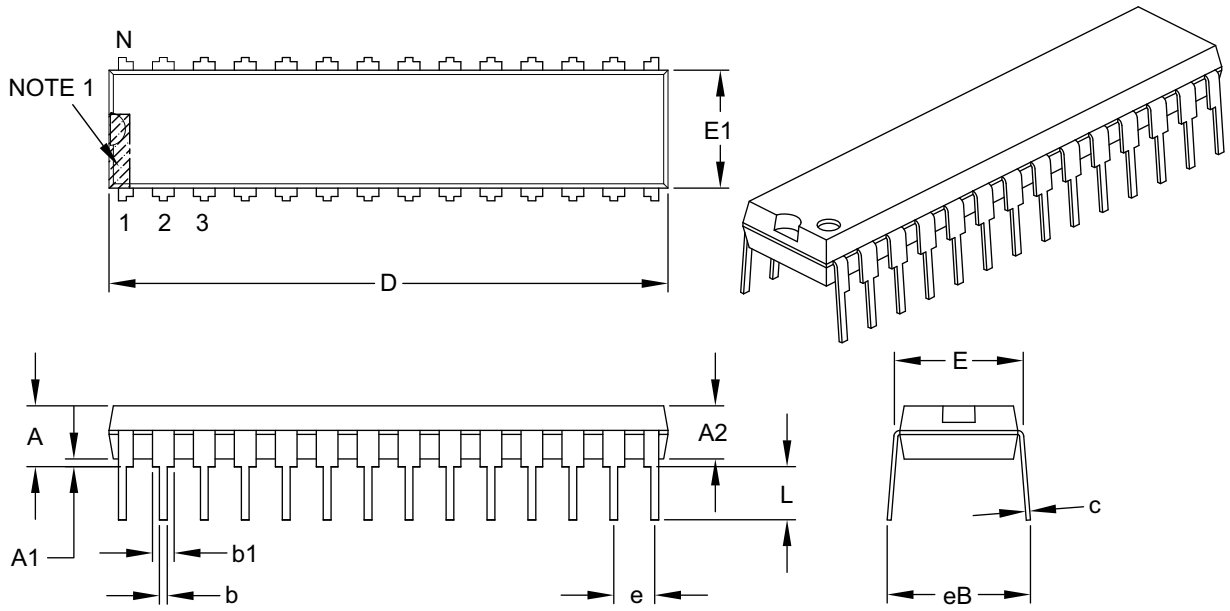
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-094C Sheet 2 of 2

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

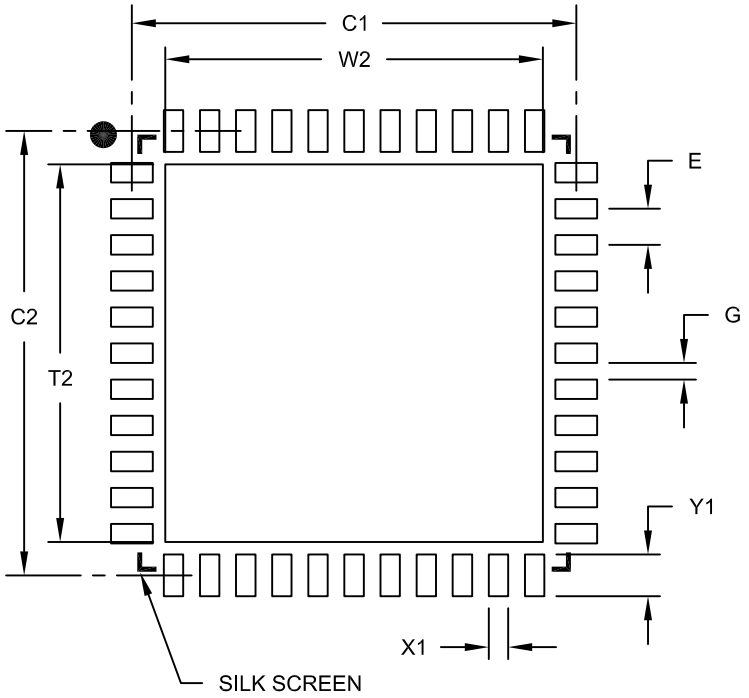
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			6.60
Optional Center Pad Length	T2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103B